# **ON Semiconductor**

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# Product Preview

# Field Stop Trench IGBT 40 A, 650 V

Using the novel field stop generation IGBT technology, ON Semiconductor's new series of field stop 4<sup>th</sup> generation of RC IGBTs offer superior conduction and switching performance and easy parallel operation. This device is well suited for the resonant or soft switching application such as induction heating and microwave oven.

#### **Features**

- Maximum Junction Temperature:  $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)} = 1.36 \text{ V (Typ.)} @I_C = 40 \text{ A}$
- 100% of the Parts tested for I<sub>LM</sub> (Note 1)
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- RoHS Compliant
- IGBT with Monolithic Reverse Conducting Diode

#### **Typical Applications**

- Induction Heating
- Microwave Oven
- Soft Switching Application

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector to Emitter Voltage	V <sub>CES</sub>	650	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage	V <sub>GES</sub>	±20 ±30	V
Collector Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	I <sub>C</sub>	80 40	Α
Pulsed Collector Current (Note 1)	I <sub>LM</sub>	120	Α
Pulsed Collector Current (Note 2)	I <sub>CM</sub>	120	Α
Diode Forward Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	IF	40 20	Α
Pulsed Diode Maximum Forward Current	I <sub>FM</sub>	120	Α
Maximum Power Dissipation $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	P <sub>D</sub>	231 115	W
Operating Junction / Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	−55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  = 120 A,  $R_{G}$  = 7  $\Omega$ , Inductive Load, 100% Tested.

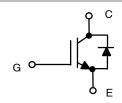
2. Repetitive rating: pulse width limited by max. Junction temperature.

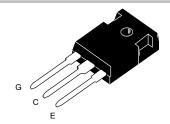


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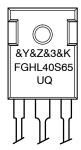
40 A, 650 V V<sub>CE(sat)</sub> = 1.36 V (Typ.)





TO-247-3L CASE 340CX

#### MARKING DIAGRAM



&Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = 3-Digit Data Code

&K = 2-Digit Lot Traceability Code FGHL40S65UQ = Specific Device Code

#### **ORDERING INFORMATION**

Device	Package	Shipping
FGHL40S65UQ	TO-247-3L	30 Units / Rail

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.65	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.69	°C/W
Thermal resistance junction-to-ambient	$R_{ heta JA}$	40	°C/W

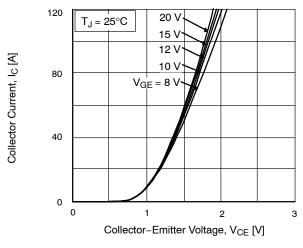
## **ELECTRICAL CHARACTERISTICS** (T<sub>.1</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTIC						
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	BV <sub>CES</sub>	650	-	_	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	$\Delta BV_{CES}/\Delta T_{J}$	-	0.5	_	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	-	-	250	μΑ
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	_	_	±400	nA
ON CHARACTERISTIC	•	•		•	•	•
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 40 \text{ mA}$	$V_{GE(th)}$	2.5	4.7	6.5	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	V <sub>CE(sat)</sub>	-	1.36 1.6	1.7 –	V
DYNAMIC CHARACTERISTIC						
Input capacitance	V <sub>CE</sub> = 30 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>ies</sub>	-	6054	-	pF
Output capacitance		C <sub>oes</sub>	-	36	_	
Reverse transfer capacitance		C <sub>res</sub>	-	30	_	
Gate charge total	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 40 A,	Qg	-	306	_	nC
Gate to emitter charge	V <sub>GE</sub> = 15 V	Q <sub>ge</sub>	-	30	_	
Gate to collector charge		Q <sub>gc</sub>	ı	99	_	
SWITCHING CHARACTERISTIC, INDUCTIVE L	_OAD					
Turn-on delay time	$T_J$ = 25°C $V_{CC}$ = 400 V, $I_C$ = 40 A, $R_G$ = 6 $\Omega$ $V_{GE}$ = 15 V Inductive Load	t <sub>d(on)</sub>	-	32	_	ns
Rise time		t <sub>r</sub>	1	20	_	
Turn-off delay time		t <sub>d(off)</sub>	1	260	_	
Fall time		t <sub>f</sub>	-	13	_	
Turn-on switching loss		E <sub>ON</sub>	-	1760	_	μЈ
Turn-off switching loss		E <sub>OFF</sub>	1	362	_	
Total switching loss		E <sub>TS</sub>	-	2122	_	
Turn-on delay time	$\begin{split} T_J &= 175^{\circ}C \\ V_{CC} &= 400 \text{ V, } I_C = 40 \text{ A,} \\ R_G &= 6 \Omega \\ V_{GE} &= 15 \text{ V} \\ \text{Inductive Load} \end{split}$	t <sub>d(on)</sub>	-	30	_	ns
Rise time		t <sub>r</sub>	-	28	_	
Turn-off delay time		t <sub>d(off)</sub>	-	284	_	
Fall time		t <sub>f</sub>	_	56	_	
Turn-on switching loss		E <sub>ON</sub>	_	2050	_	μJ
Turn-off switching loss	1	E <sub>OFF</sub>	_	590	_	
Total switching loss	1	E <sub>TS</sub>	_	2640	_	

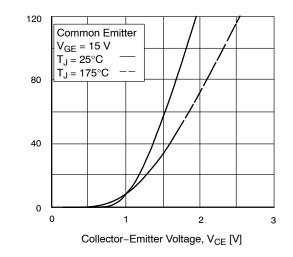
## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified) (continued)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTIC						
Forward voltage	I <sub>F</sub> = 20 A I <sub>F</sub> = 20 A, T <sub>J</sub> = 175°C	V <sub>F</sub>	- -	1.24 1.24	1.6 -	V
Reverse Recovery Energy	$I_F = 20 \text{ A}, \ \Delta I_F/\Delta t = 200 \text{ A}/\mu \text{s}$	E <sub>REC</sub>	_	359	_	μJ
Diode Reverse Recovery Time	$\begin{array}{l} I_F = 20 \; A, \; \Delta I_F/\Delta t = 200 \; A/\mu s \\ I_F = 20 \; A, \; \Delta I_F/\Delta t = 200 \; A/\mu s, \\ T_J = 175^{\circ}C \end{array}$	T <sub>RR</sub>	-	319 430	_	nS
Diode Reverse Recovery Charge	$\begin{split} I_F &= 20 \text{ A, } \Delta I_F/\Delta t = 200 \text{ A/}\mu\text{s} \\ I_F &= 20 \text{ A, } \Delta I_F/\Delta t = 200 \text{ A/}\mu\text{s}, \\ T_J &= 175^{\circ}\text{C} \end{split}$	Q <sub>RR</sub>	-	1853 3007	-	nC

#### **TYPICAL CHARACTERISTICS**



**Figure 1. Typical Output Characteristics** 



Collector Current, Ic [A]

Figure 3. Typical Saturation Voltage Characteristics

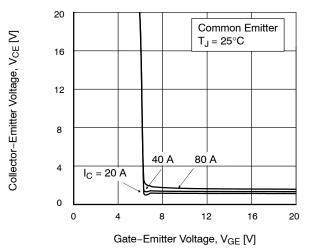


Figure 5. Saturation Voltage vs V<sub>GE</sub>

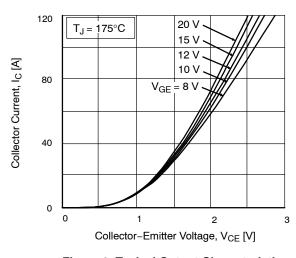


Figure 2. Typical Output Characteristics

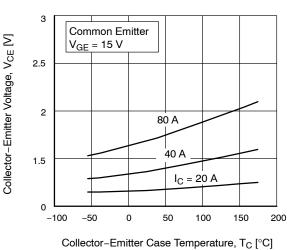


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

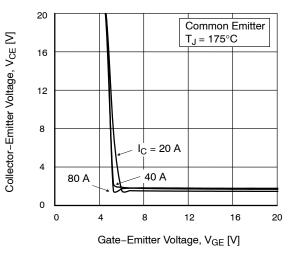


Figure 6. Saturation Voltage vs V<sub>GE</sub>

#### TYPICAL CHARACTERISTICS (continued)

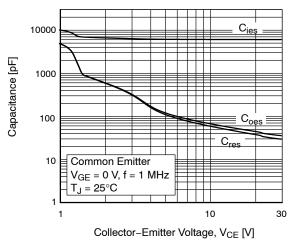


Figure 7. Capacitance Characteristics

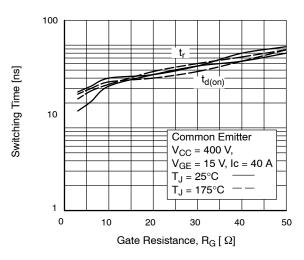


Figure 9. Turn-on Characteristics vs. Gate Resistance

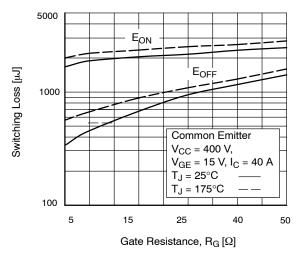


Figure 11. Switching Loss vs Gate Resistance

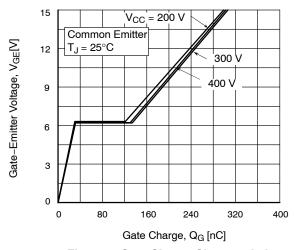


Figure 8. Gate Charge Characteristics

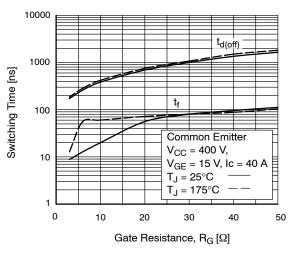


Figure 10. Turn-Off Characteristics vs. Gate Resistance

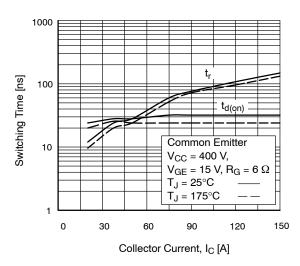


Figure 12. Turn-On Characteristics vs. Collector Current

#### TYPICAL CHARACTERISTICS (continued)

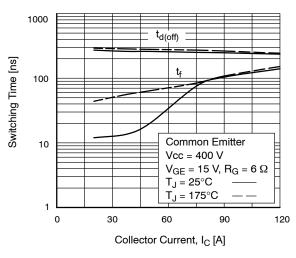


Figure 13. Turn-Off Characteristics vs.
Collector Current

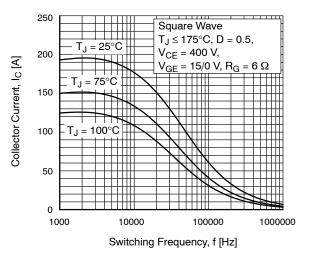


Figure 15. Load Current vs Frequency

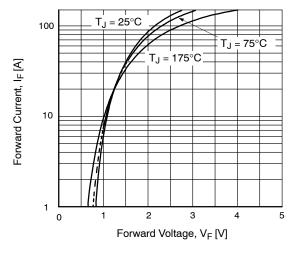


Figure 17. Forward Characteristics

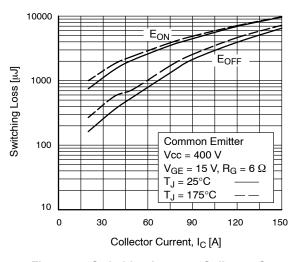


Figure 14. Switching Loss vs. Collector Current

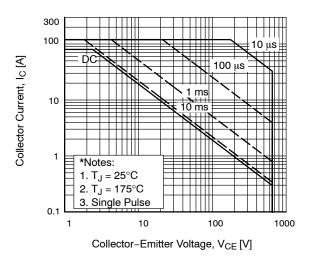
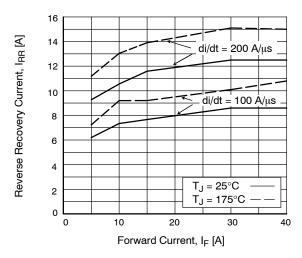
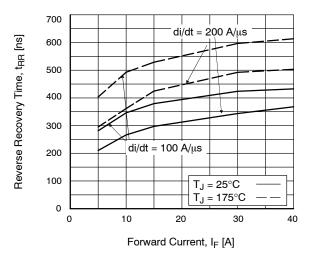


Figure 16. SOA Characteristics (FBSOA)



**Figure 18. Reverse Recovery Current** 

## TYPICAL CHARACTERISTICS (continued)



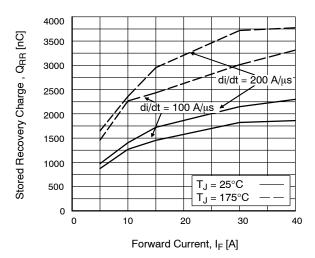


Figure 19. Reverse Recovery Time

Figure 20. Stored Charge

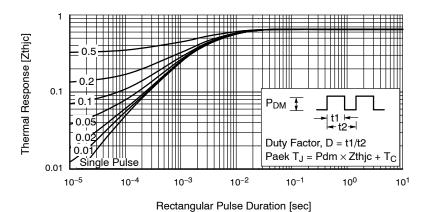


Figure 21. Transient Thermal Impedance of IGBT

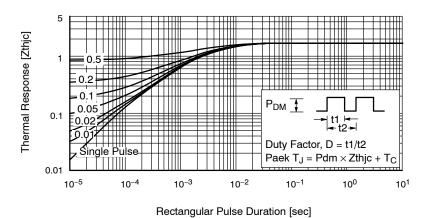
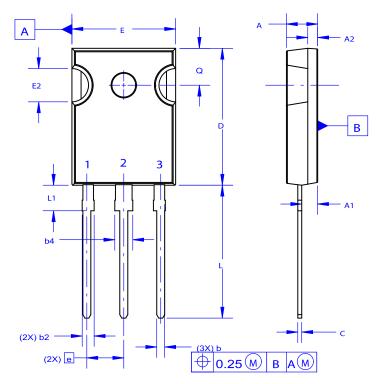


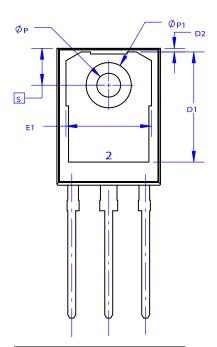
Figure 22. Transient Thermal Impedance of Diode

TO-247-3LD CASE 340CX ISSUE O



#### NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
  C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
<b>A</b> 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	1		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	1		
D2	0.51	0.93	1.35		
E1	12.81	~	1		
ØP1	6.60	6.80	7.00		

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